

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	EMBEDDED PROCESSING/26/16284	
1.3 Title of PCI	JSCC (China) – Leadframe redesign for molding machine compatibility on the VQFPN 8x8 68L package	
1.4 Product Category	STM32H56x, STM32H57x, STM32H72x, STM32H73x, STM32H7Rx, STM32H7Sx, STM32WB55x and STM32WBA6x	
1.5 Issue date	2026-09-01	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Leadframe - Any Other change: design, etc.)	JSCC (China)

4. Description of change

	Old	New
4.1 Description	Current Mold Machine: ASM, Current Leadframe design is only for ASM machine	New Mold Machine: TOWA New Strip outline of Lead frame was redesigned to meet layout of new molding machine.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on final product	

5. Reason / motivation for change

5.1 Motivation	ST VQFN8X8 demand is increase and JSCC will phase out old ASM machine, so to qualify TOWA machine for capacity increase. Due to different mold machine model, Strip outline of Lead frame need redesign to meet new layout of molding machine
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools.
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7. Timing / schedule

7.1 Date of qualification results	2026-08-10
7.2 Intended start of delivery	2026-10-05
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	16284 MDG-MCD RERMCD1524 - STM32F7x- Die 452XXA - Reliability Evaluation Report - REV1.3.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-09-01

9. Attachments (additional documentations)		
16284 Public product.pdf 16284 MDG-MCD RERMCD1524 - STM32F7x- Die 452XXXA - Reliability Evaluation Report - REV1.3.pdf 16284 _Additional information.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32WB55REV6TR	

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